



Applied Electronics

C7 – Signal Integrity

- Crosstalk
- Techniques to limit crosstalk
- Switching noise
- Bypass Capacitors

Lecture C7: Signal integrity

- Crosstalk
 - ◆ Capacitive and inductive couplings
 - ◆ Direct and reverse crosstalk
 - ◆ Techniques to reduce crosstalk
- Switching noise
 - ◆ Ground distribution and power supply
 - ◆ Techniques for reducing switching noise
 - ◆ Bypass capacitors
- References
 - ◆ D. Del Corso: Telecommunication Electronics: Ch. 5.2.10

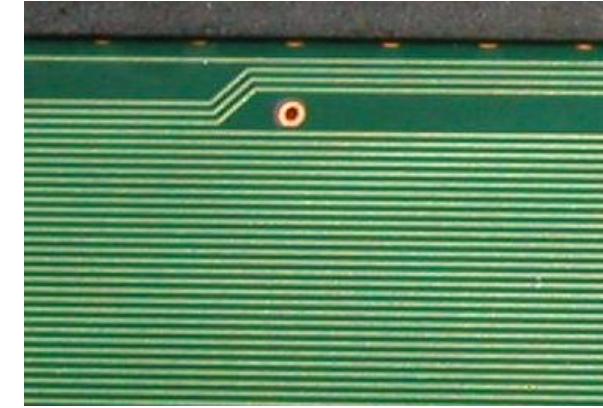
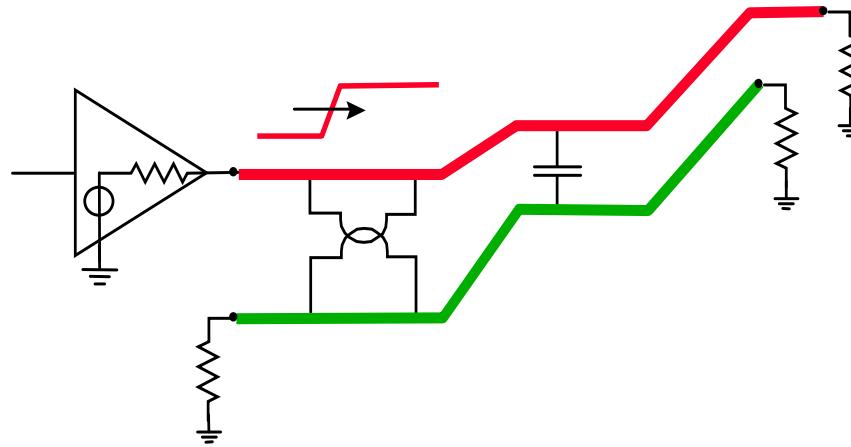
Crosstalk

- Crosstalk
 - ◆ Signal passing between two “channels”
 - Separated by space, time, encodings, ...
- Between different conductors:
 - ◆ Inductive and capacitive couplings (rarely resistive)
- On the same conductor (GND, signals, supply)
 - ◆ Coupling for common traces
 - ◆ Power impulse currents disturb the signals
- In time domain
 - ◆ “Code” in symbols → Intersymbol Interference (ISI)

Coupling between conductors

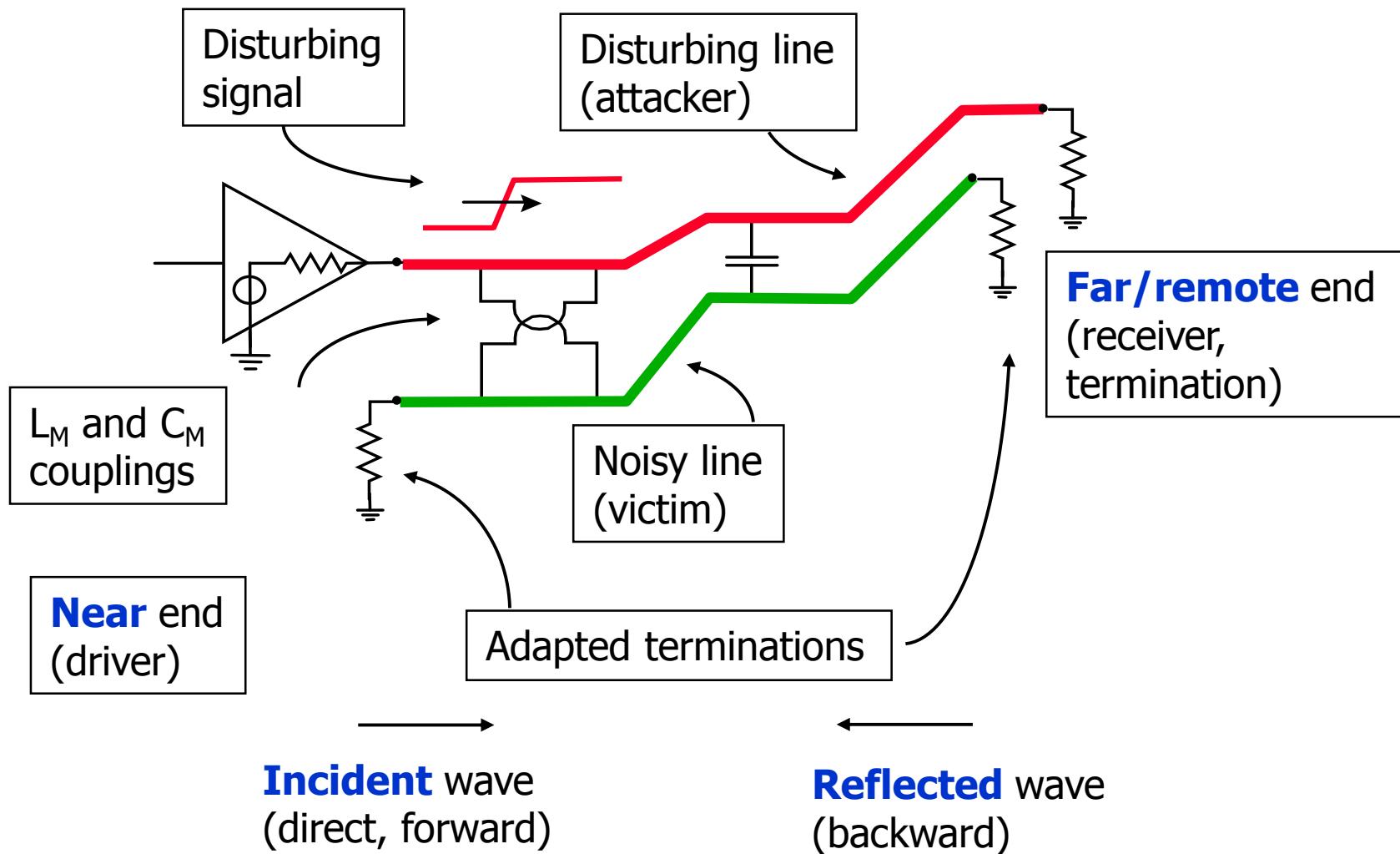
Adjacent conductors have

- ◆ Inductive couplings
 - L_M – mutual inductance
- ◆ Capacitive couplings
 - C_M – mutual capacitance



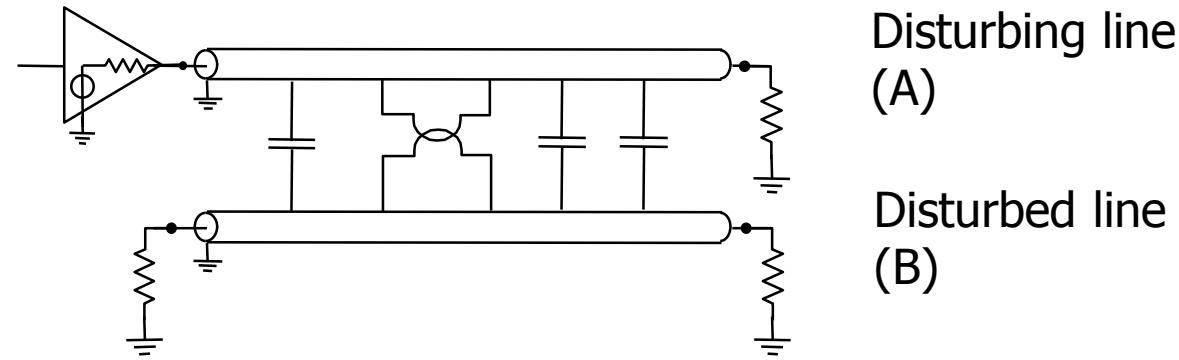
L_M and C_M are
distributed over the
whole conductor length

Terminology

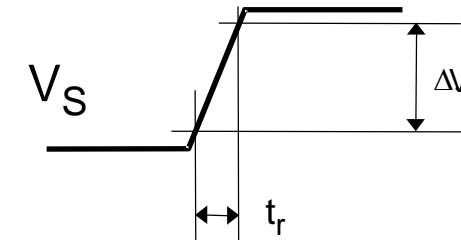


System model and signals

- Line model
 - ◆ Two lines adapted to the driver and the termination, with **mutual inductance L_M** and **mutual capacitance C_M**

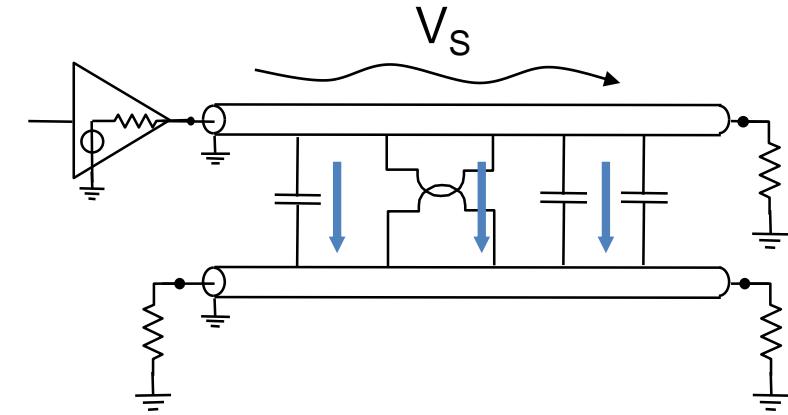


- Disturbing signal (V_S)
 - ◆ **Trapezoidal** shape (finite dv/dt)



Coupling parameters

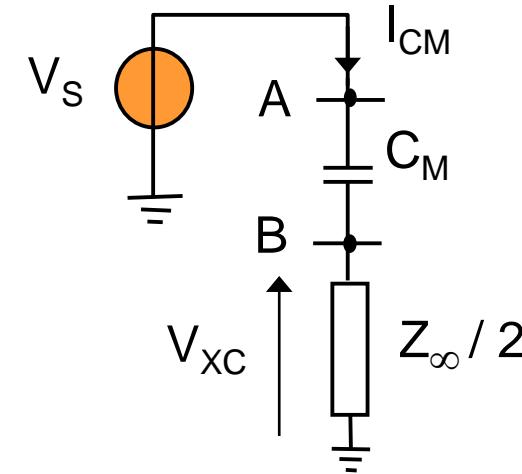
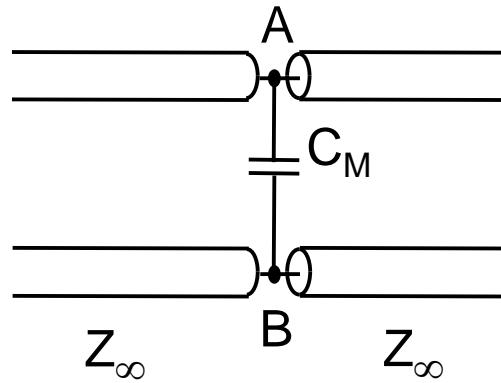
- The V_S signal propagates along the *top line*
- Inductive couplings (L_M) and capacitive (C_M) generate **noise** in the *bottom line*
- Noise is related to
 - ◆ Edge **slopes** of the disturbing signal (dV_S/dt , dI_S/dt)
 - ◆ Mutual inductance L_M
 - ◆ Mutual capacitance C_M



Capacitive coupling model

- **Capacitive couplings** inject a current I_{CM} that causes a voltage variation proportional to dV_S/dt

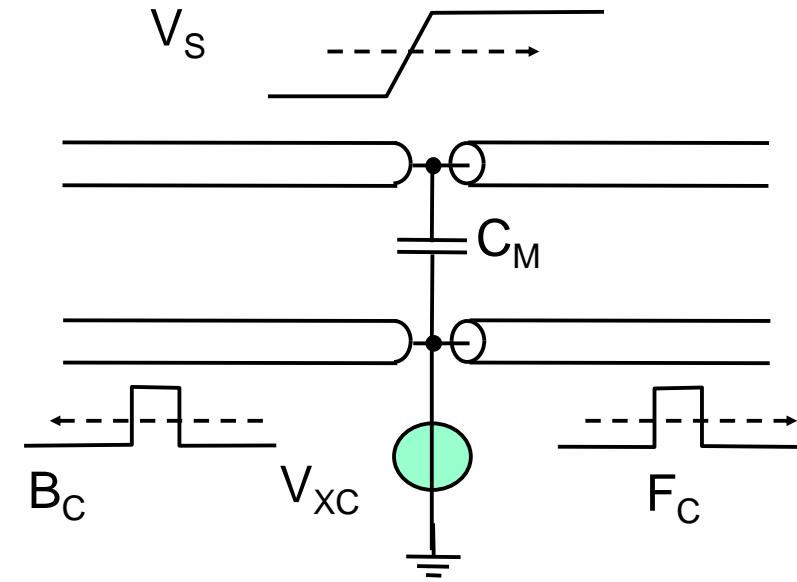
$$V_{XC} = Z_\infty / 2 \quad I_{CM} = Z_\infty / 2 \quad C_M \quad dV_S / dt \quad (V_B \text{ constant})$$



Effect of capacitive coupling

- V_{XC} has the same sign as the disturbing signal
- V_{XC} propagates with the same polarity in both directions

V_{XC} pulse width
is equal to the
rise time of V_S



Overall effect C_M and L_M

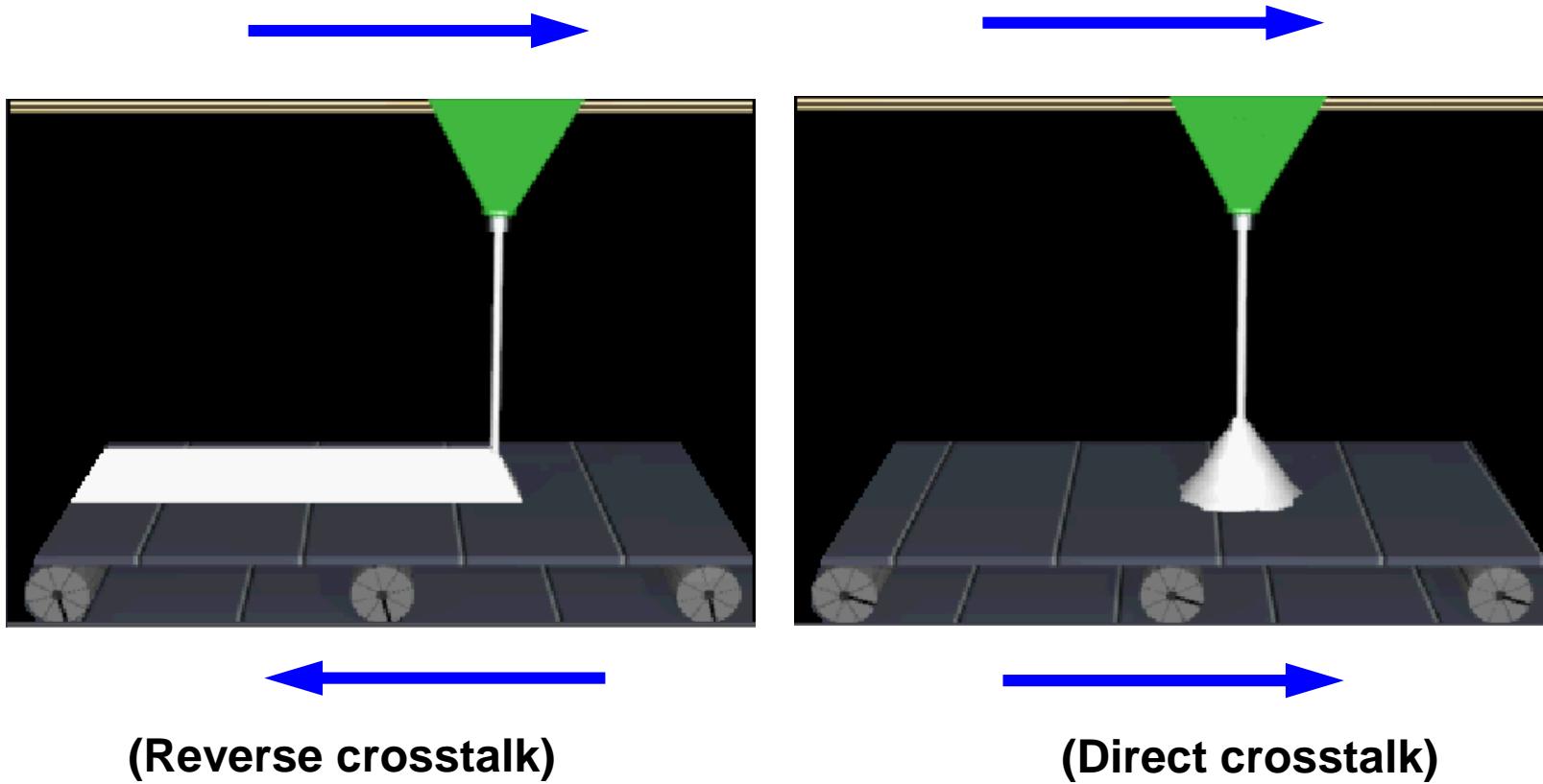
- Inductive coupling (L_M): V_{X_L} is similar to V_{X_C}
 - ◆ Total noise: sum of the two effects
- **Progressive wave** (V_P) towards the termination, →
 - ◆ $V_P = (V_{X_C} - V_{X_L})/2$
- **Regressive wave** (V_R) towards the driver, ←
 - ◆ $V_R = (V_{X_C} + V_{X_L})/2$
- V_{X_L} and V_{X_C} have opposite signs in progressive wave
 - ◆ The two contributions can **compensate** each other
- **Equal propagation speed**
 - ◆ Equal to the propagation speed of electromagnetic waves in that conductor

Sum of noise

- Same speed as the noise signal, so ...
- Noise that propagate towards the termination
 - ◆ Direct crosstalk →
 - Sum of noise generated as the step propagates (the induced noise and its “source” move at the same speed)
 - Total noise of **constant width** (t_r), **variable amplitude** depending on the position along the line and the length of the adjacent track
- Noise that propagates to the driver
 - ◆ Reverse crosstalk ←
 - The additional noise generated merge over time (the amplitudes do not add up)
 - Total noise has **constant amplitude**, **variable duration** depending on the line position and the length of the adjacent track (max 2 t_P)

Mechanical analogy

- Hopper and conveyor belt

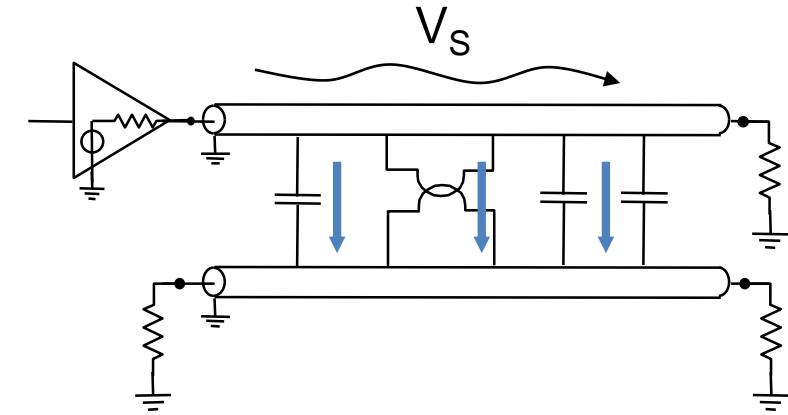


Observable signals

- Direct crosstalk
 - ◆ Conveyor belt and hopper move in the same direction
 - Cumulus cone: height gradually increasing
 - ◆ Constant duration, t_r
 - ◆ Variable amplitude with the position: max at the far end
- Reverse crosstalk
 - ◆ Conveyor belt and hopper move in opposite directions
 - Strip heap: constant height, increasing length
 - ◆ Constant amplitude
 - ◆ Variable duration with position: max ($2 t_P$) to the driver
- On the line always appears the sum of the two

Coupling parameters

- The V_S signal propagates along the top line
- Inductive couplings (L_M) and capacitive (C_M) generate **noise** in the lower line
- Noise is related to
 - ◆ **Slope** of the noise edge (dV_S/dt , dI_S/dt)
 - ◆ Mutual inductance L_M
 - ◆ Mutual capacitance C_M

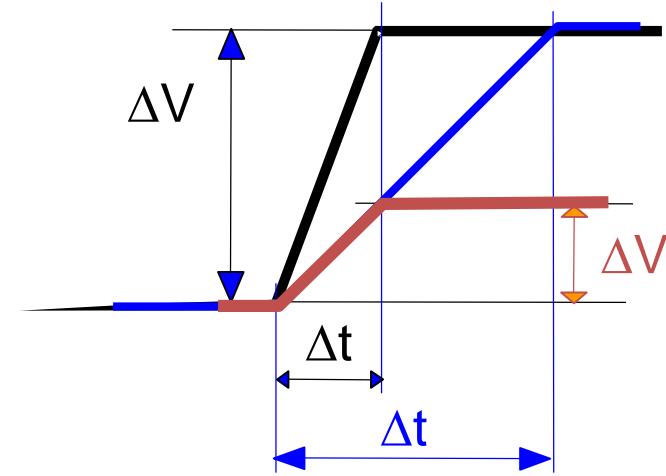


Keep an eye on crosstalk

- Crosstalk is related to
 - ◆ Speed of the edges of the noise signal (dv/dt)
 - ◆ L and C couplings
 - ◆ Noise margin of the receiver
- To reduce the crosstalk
 - ◆ Slow down the driver edges on the noisy lines
 - ◆ Reduce C_M and L_M
 - ◆ Use differential signals
- To reduce the effects of crosstalk
 - ◆ Filter the receivers of the line affected by noise
 - ◆ Error Detection and Correction Techniques (EDC/ECC)

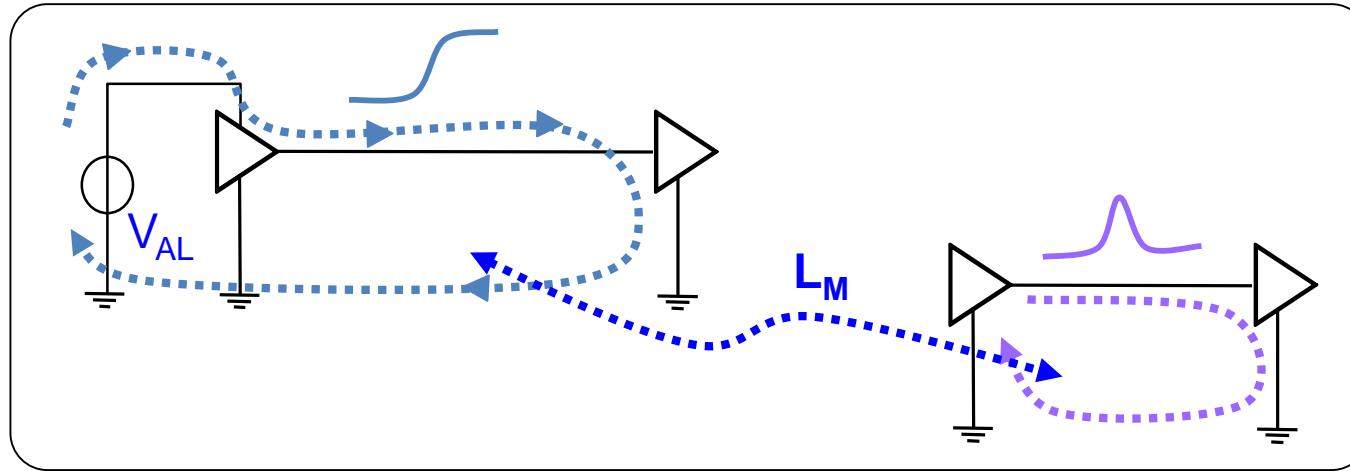
Reduce the slope of the fronts

- Slope = $dv/dt = \Delta V/\Delta t$
- Reduce ΔV
 - ◆ Transceiver family with low voltage range
 - ◆ Differential signals with compensating opposite effects (LVDS)
- Increase Δt
 - ◆ Use slower logic (still compatible with the specifications)
 - ◆ Slower is always good: it reduces consumption and noise



Inductive couplings

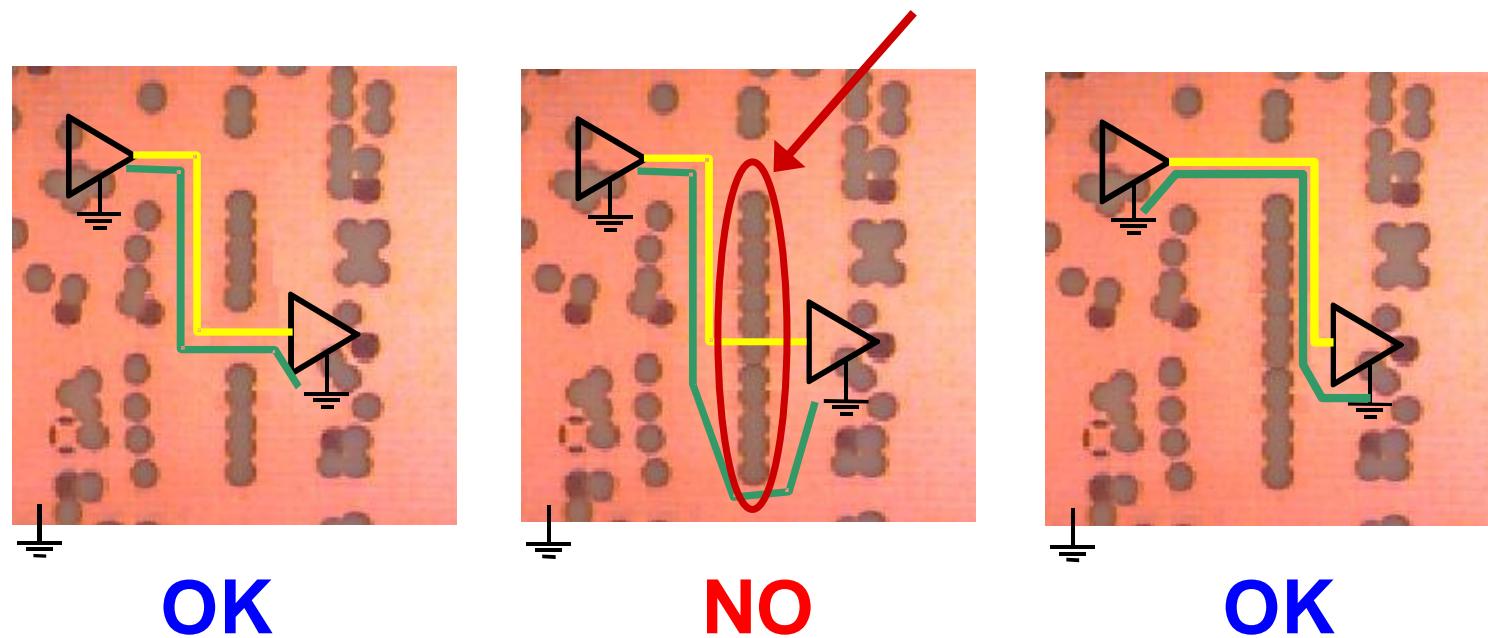
- The signal and return current go through one loop



- The mutual inductance L_M between two loops depends on distance, embedded area, materials, ...
- To reduce L_M **avoid wide and embedded loops**
 - Keep **close** the signal and return (ground) tracks

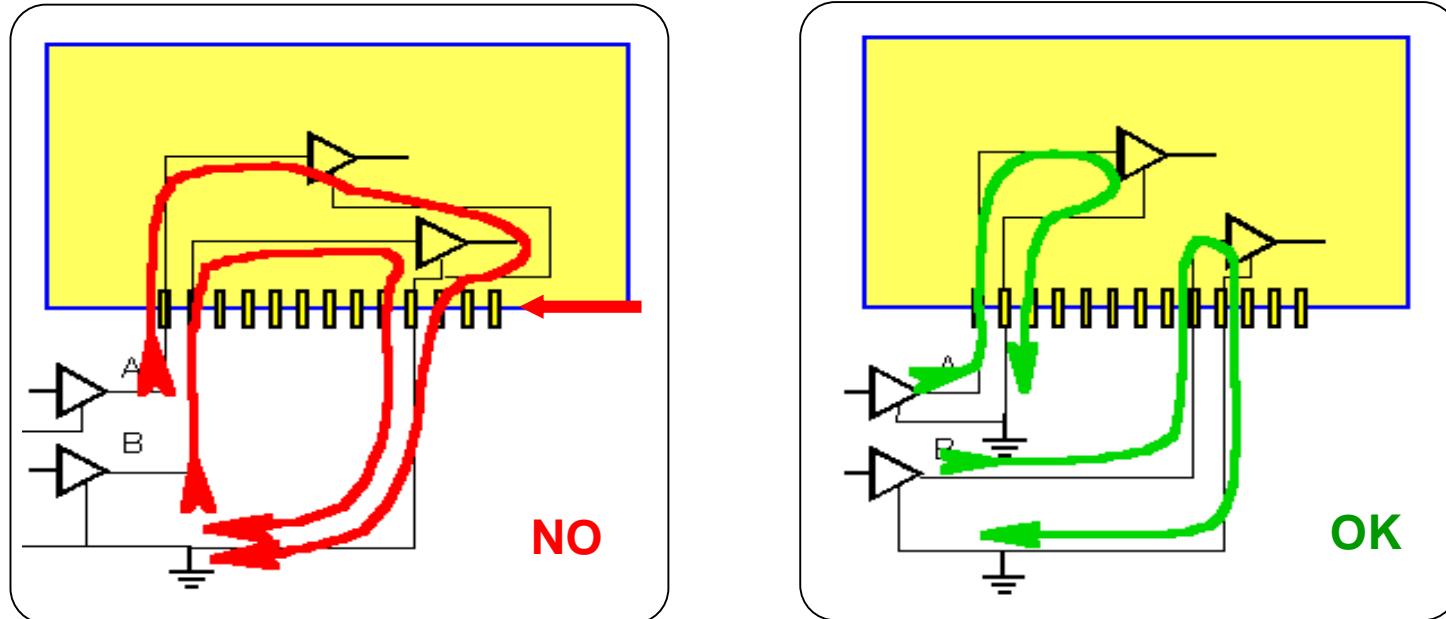
Return currents paths

- The **return currents** follow paths with minimal area
 - ◆ Spend less energy to create the magnetic field
- The return currents flow “close” to the signal
 - **Continuous ground plane, without cuts**



Reduce inductive couplings

- Nested loops include shared ground paths
 - ◆ **Separate** ground connections per signal to avoid inductive couplings (also reduce capacitive couplings)



Differential signals

- **Advantages**

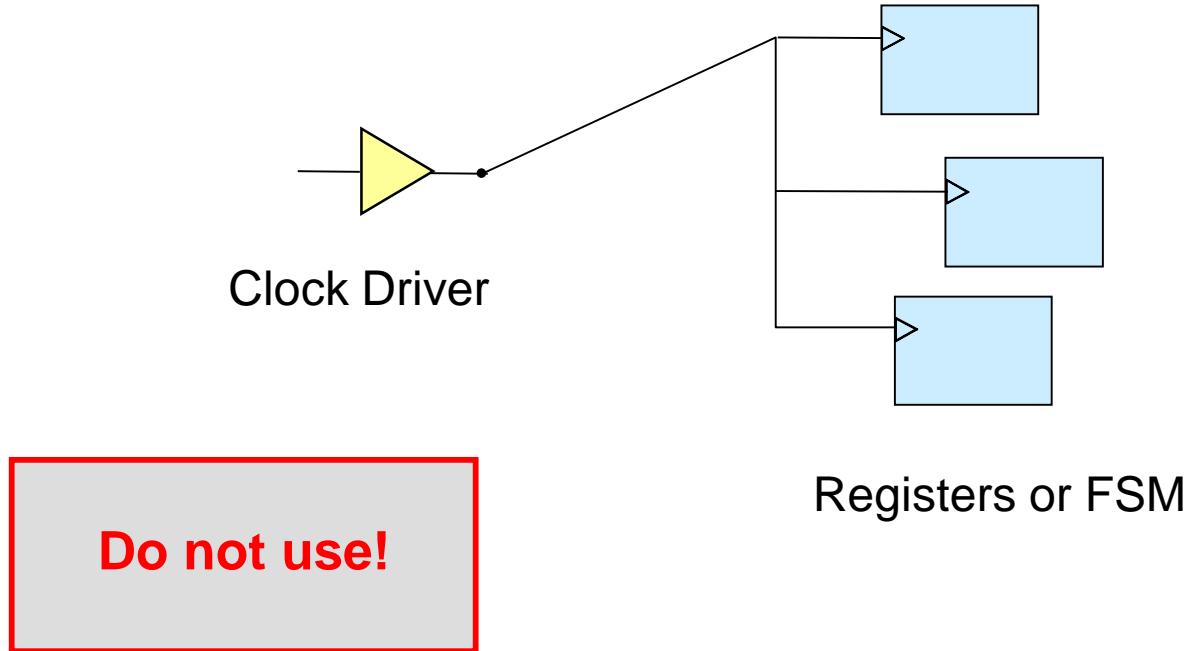
- ◆ Noise is common mode and is strongly rejected
 - Allow to **reduce the voltage amplitude of the signal**
 - **Lower ΔV** → lower consumption and interference (crosstalk, EMI)
- ◆ The total current in a differential pair is constant
 - The current is switched from one conductor to the other
 - **Constant absorption** from the power supply
 - **Lower** interference (**EMI**)

- **Disadvantages**

- ◆ 2 tracks/pins for each signal
- ◆ Require “analog” techniques (differential stages, ...)

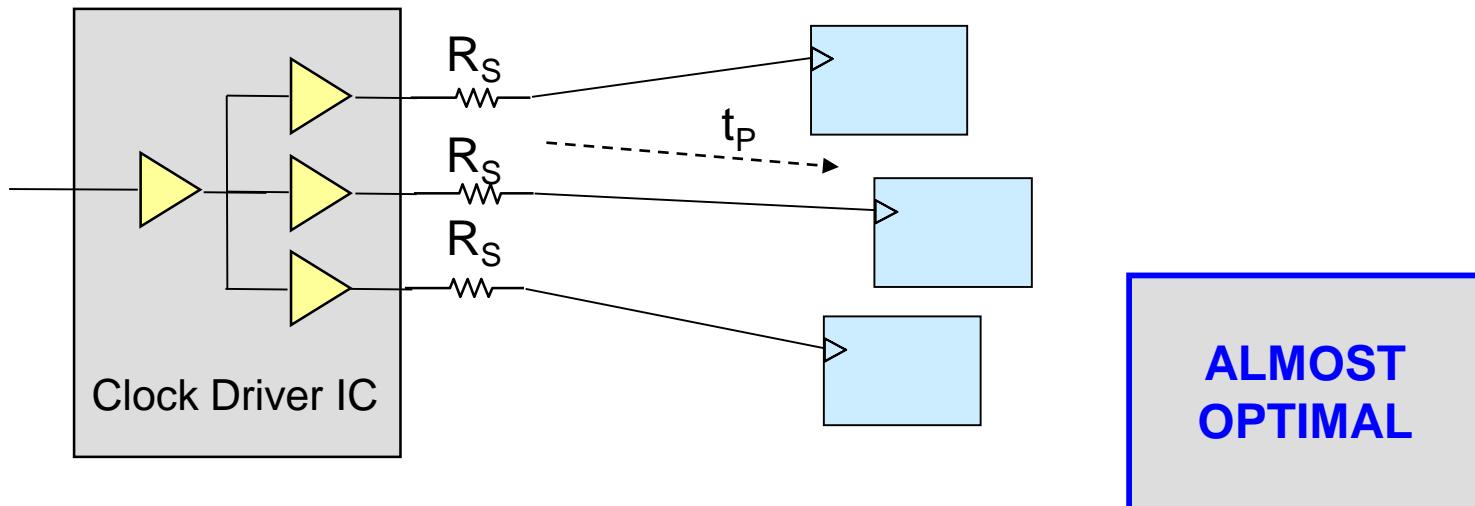
Clock distribution

- Multi-point chain connection → high skew
- The clock arrives at different times at the registers



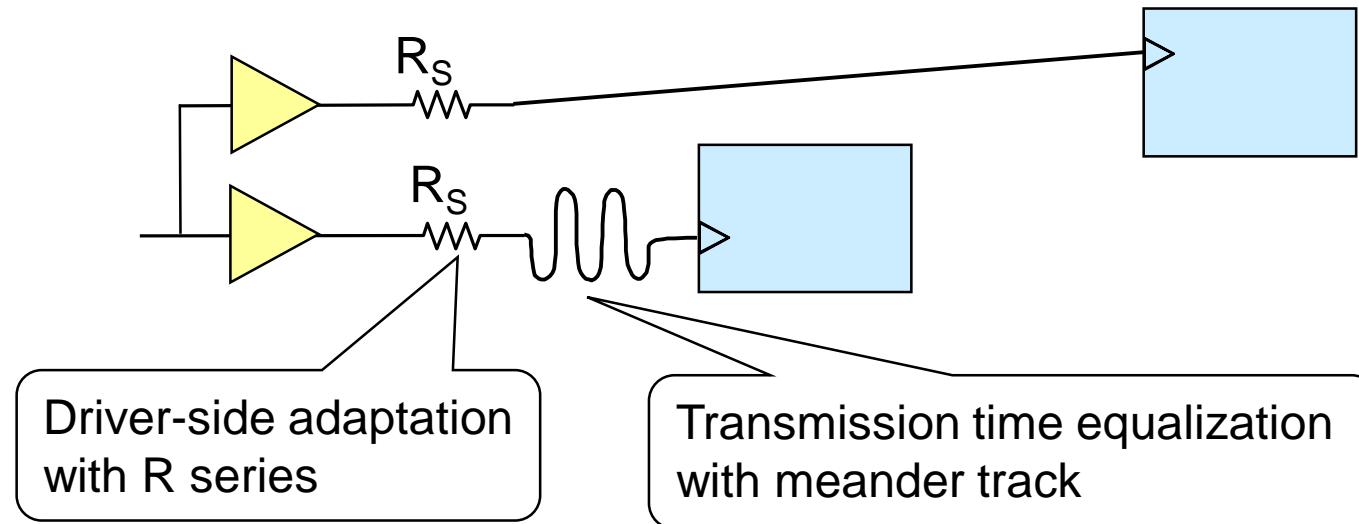
Distribution with clock driver

- Separate devices for driving multiple clocks
 - ◆ Delays are known and controlled
 - ◆ Driver-side adaptation (near end): $R_S = Z_\infty - R_O$
 - ◆ Reflection at termination (RWS, reflected wave switching)
 - ◆ Maximum transmission time (to the driver) $t_{TXmax} = 2 t_P$

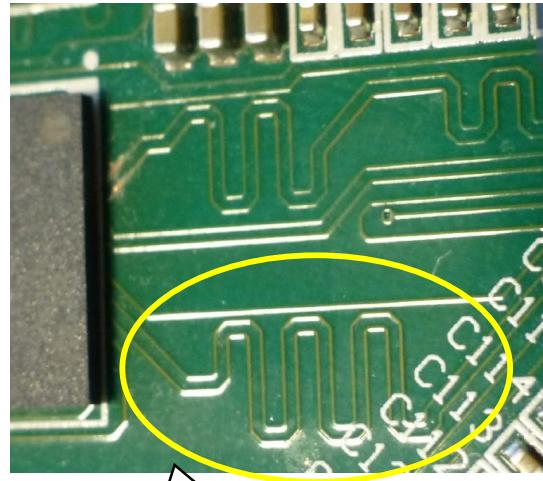


Equalization of delays

- Use separate devices when driving multiple clocks
 - ◆ Known and controlled delays, driver-side adaptation (near end): Reflected Wave Switching: $t_{TXmax} = 2 t_P$
- Same length for all paths (use of meanders to equalize the t_P)

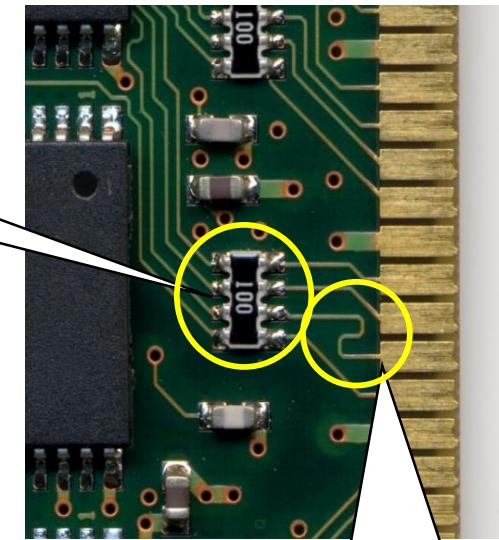


PCB examples (memory)



Meander track for differential signals (2 conductors)

Series **termination** resistances (4)



Meander track to equalize the transmission times

Lecture C7: Power distribution

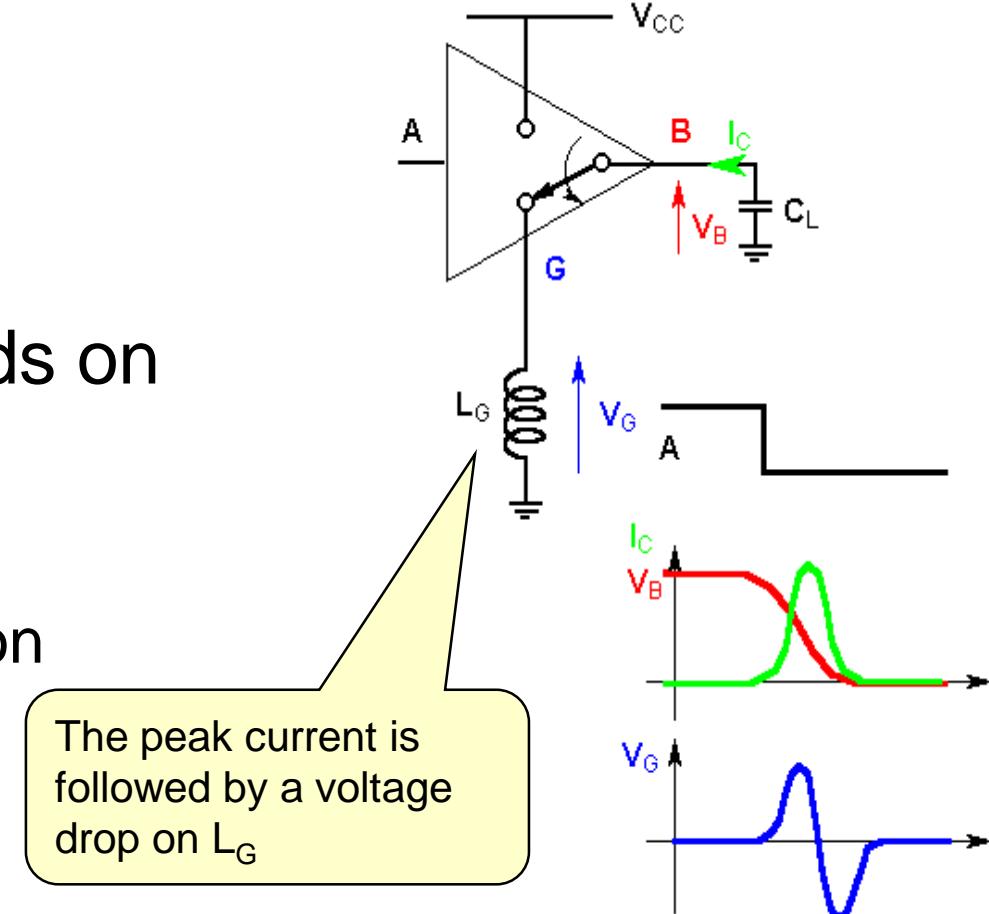
- Crosstalk
 - ◆ Capacitive and inductive couplings
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 - ◆ Bypass Capacitors

Couplings from common connections

- The currents that supply different parts of the circuit can have **common paths**
 - ◆ Static voltage drop (constant I): $\Delta V = R I$
 - ◆ **Dynamic** voltage drop that is caused by changes in the current during switching: $\Delta V = L dI/dt$
- **Ground bounce**
 - ◆ Pulsed currents cause shifts of the reference
$$\Delta V = L dI/dt; \quad I = C dV/dt; \quad \Delta V = L C d^2V/dt^2$$
- Simultaneous switching of several outputs
 - ◆ **Simultaneous switching** noise

Impulsive currents: V_{CC} – GND

- C_L discharge current flows in the GND conductor, and V_G varies
- **Ground Bounce**
- Ground bounce depends on
 - ◆ Load capacitance C_L
 - ◆ dV/dt slope of V_B
 - ◆ L_G of the GND connection
- For L-H transitions Same effect on V_{CC}
 - ◆ V_{CC} Sag or Power Bounce

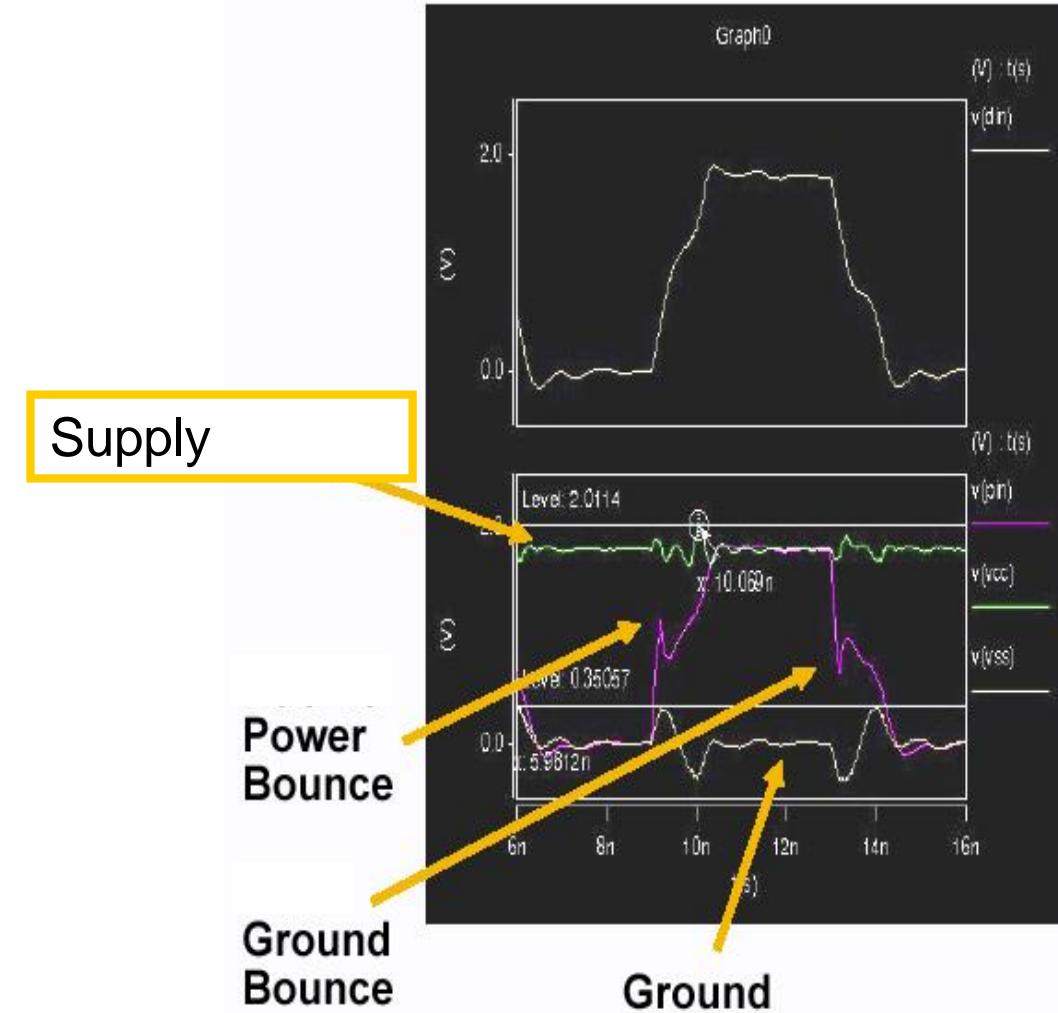


Switching noise

- Ground bounce and switching noise related to
 - ◆ Slope of transitions (dV/dt)
 - ◆ Charge quantity to be moved (load capacitance C_L)
 - ◆ Inductance of the GND and power connections (L_G, L_S)
- Voltage variations on GND and power supplies
 - ◆ Concern devices with common ground and power supply
 - Other logic gates of the same component
 - Other neighboring components (same ground and power supply)
 - ◆ They cause variations of
 - Actual input voltages
 - Output voltages
 - ◆ They can determine oscillations

Effects of ground and power bounce

- **Ground bounce**
 - ◆ It can transform a logical 0 into 1
- **Power bounce**
 - ◆ Similarly, it can turn a 1 into 0
- Both worsen the noise margins



Ground bounce and switching noise

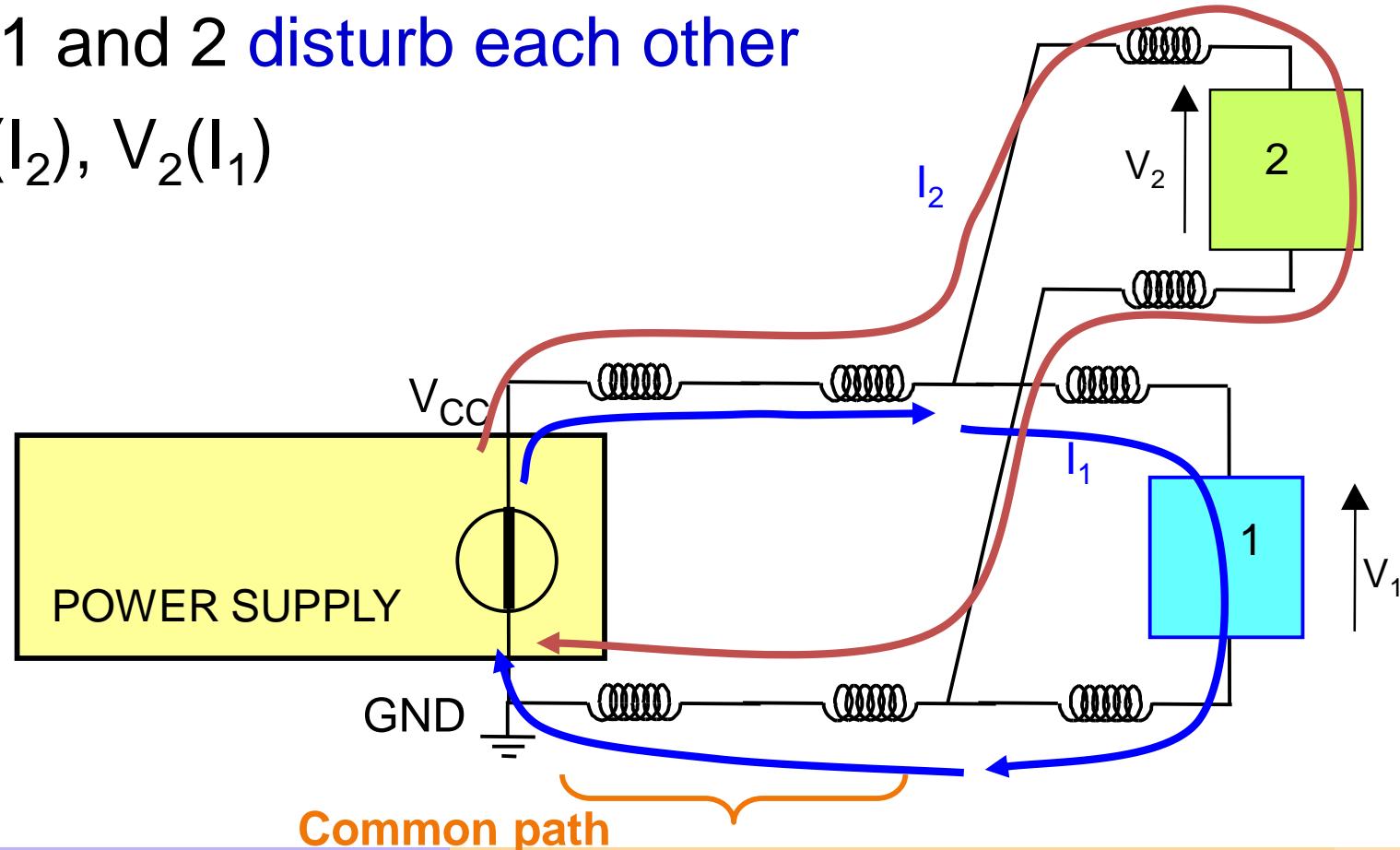
- **Switching noise** related to # of outputs changing state
 - ◆ For each output
$$\Delta V = L \frac{dI}{dt}; \quad I = C \frac{dV}{dt}; \quad \Delta V = L C \frac{d^2V}{dt^2}$$
 - ◆ Speed of the edges
 - ◆ Load capacitance
 - ◆ V_{CC} and GND inductance
- Switching noise shifts ground and supply
- Affects other gates of the same integrated circuit
 - ◆ Common ground and power supplies
 - ◆ Change the input threshold
 - ◆ Change the output levels

Reduce switching noise

- Objectives
 - ◆ Create **low impedance paths** for impulse currents
 - ◆ Current peaks supplied by nearby “charge tanks”
- Decoupling Capacitors (bypass)
 - ◆ Placed close to the ICs that drive low impedance loads
 - ◆ Create low inductance paths for impulse currents
 - ◆ Recharge slowly, without current pulses
- Necessary
 - ◆ Capacitors with **low Equivalent Series Resistance (ESR)** and **low Equivalent Series Inductance (ESL)**
 - ◆ Use appropriate layout criteria

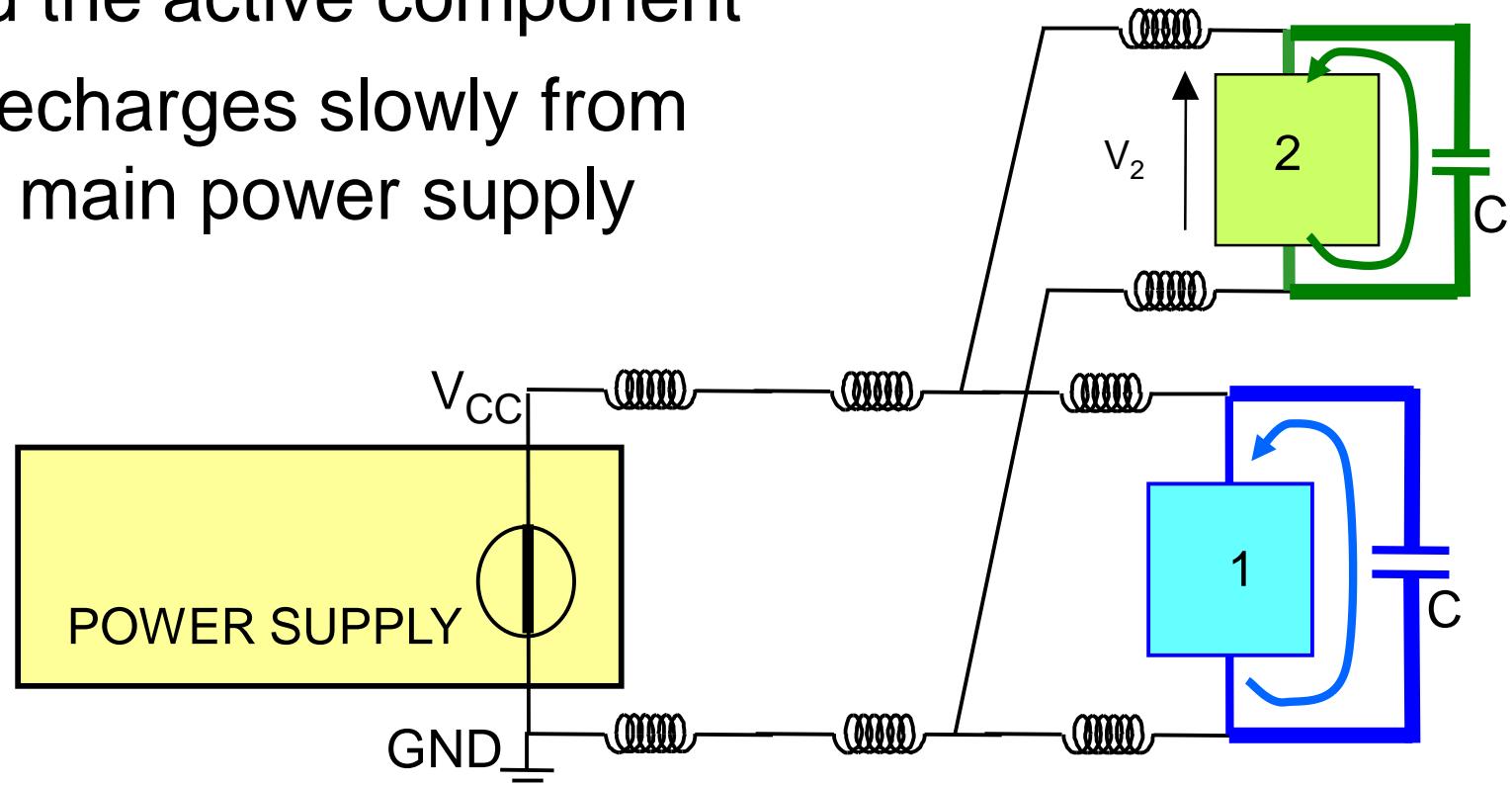
Path of the currents

- All currents come from the power supply, and determine voltage drops on inductances
→ 1 and 2 **disturb each other**
- $V_1(I_2)$, $V_2(I_1)$



Bypass Capacitors

- Impulse currents are supplied by the capacitors C
- Flow only on low impedance tracks between C and the active component
- C recharges slowly from the main power supply



Value of the bypass capacitors

- Purpose: limit the ripple on power supply and GND
- Q = charge stored in the capacitor
- V = Voltage across the capacitor
 - ◆ ΔV = max voltage variation allowed
 - ◆ Δt = duration of capacitor supply (ground bounce duration)
 - ◆ $\Delta Q = C \Delta V; I = \Delta Q / \Delta t = C \Delta V / \Delta t$
 - ◆ $C = I \Delta t / \Delta V$
 - ◆ Considering the equivalent series resistance of C (ESR)
$$C = I \Delta t / (\Delta V - I \cdot ESR)$$
- If ESR is high → use several **parallel capacitors**
 - ◆ Multiple bypass C , of different values

Example: Switching noise

- The switching noise depends on the current peak and the inductance of the power supply connection (R series of ideal power supply is $\text{ESR} = 0 \Omega$)
- Peak current: $I = 0.2 \text{ A}$, triangular, 2 ns duration
 - ◆ $dI/dt = 0.2 \text{ A} / 2 \cdot 10^{-9} \text{ s} = 0.1 \cdot 10^9 \text{ A/s}$
- Inductance of the V_{CC} connection: $L = 10 \text{ nH}$
 - ◆ $\Delta V_{CC} = L dI/dt = 10 \cdot 10^{-9} \text{ H} \cdot 0.1 \cdot 10^9 \text{ A/s} = 1 \text{ V}$
- Value of the bypass capacitor to have $\Delta V_{CC} = 0.1 \text{ V}$
 - ◆ With $\text{ESR} = 0 \Omega$: $C = I \Delta t / \Delta V = 0.2 \text{ A} \cdot 2 \cdot 10^{-9} \text{ s} / 0.1 \text{ V} = 4 \text{ nF}$
 - ◆ With $\text{ESR} = 3 \Omega$: the drop on $\text{ESR} = 0.6 \text{ V} > \Delta V_{CC} = 0.1 \text{ V}$
 - **Impossible!** Must use several C in parallel to reduce the ESR

Lecture C7: final questions

- Explain the term “crosstalk”
- What are the effects of inductive and capacitive couplings between the tracks of a printed circuit?
- How do common paths create crosstalk?
- Should you use a slow or a fast logic family To reduce crosstalk interference?
- Recommended topology for clock distribution?
- What are simultaneous switching noise and ground bounce?
- Why are used bypass capacitors on power supplies?